

Abstract

A method for packaging a semiconductor device wherein a chip is interconnected with a substrate by performing a flip-chip bonding by using an Au bump formed on a bond pad of the chip. In the method, a wire-bonding process and a molding process using an epoxy molding compound are not required. Further, a process of attaching solder balls to the substrate is not required, which eliminates subsequent flux printing and deflux processes. Accordingly, a packaging process of the semiconductor device becomes simplified and therefore the cost of the semiconductor device is decreased.